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United States Patent [19]

Suski et al.

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[45] **Date of Patent: **Dec. 12, 1995**

[54] **SOLDER PAD FOR PRINTED CIRCUIT BOARDS**

[75] Inventors: **Edward D. Suski**, Lake Forest; **David J. Silva**, Trabuco, both of Calif.; **Glenn G. Miner**, Weatherford, Tex.

[73] Assignee: **AST Research, Inc.**, Irvine, Calif.

[**] Term: **14 Years**

[21] Appl. No.: **26,966**

[22] Filed: **Aug. 10, 1994**

[52] **U.S. Cl.** **D13/154**; D13/182

[58] **Field of Search** D8/30, 70; 228/20, 228/51, 55; 219/229, 238, 227, 233; 439/82, 78, 80, 81, 82, 84, 552, 55; D13/154, 182

[56] **References Cited**

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Primary Examiner—Alan P. Douglas
Assistant Examiner—Robert M. Spear
Attorney, Agent, or Firm—Lyon & Lyon

[57] **CLAIM**

The ornamental design for a solder pad for printed circuit boards, as shown and described.

DESCRIPTION

FIG. **1** is a front plan view of a solder pad for printed circuit boards of the present invention;

FIG. **2** is a rear plan view thereof;

FIG. **3** is a left side elevational view of the solder pad, as viewed from the left side of the page. FIG. **3** is not drawn to scale, and the thickness is exaggerated in order to illustrate that the solder pad does have a measurable thickness to it;

FIG. **4** is a top side elevational view of the solder pad, as viewed from the top side of the page. FIG. **4** is not drawn to scale, and the thickness is exaggerated in order to illustrate that the solder pad does have a measurable thickness to it. The right side and bottom side elevational views are not shown, since the symmetry of the solder pad provides a right and bottom view which is the same as the left and top view;

FIG. **5** is a front plan view of an alternative embodiment of a solder pad for printed circuit boards of the present invention;

FIG. **6** is a rear plan view thereof;

FIG. **7** is a left side elevational view of the alternative embodiment of the solder pad, as viewed from the left side of the page. FIG. **7** is not drawn to scale, and the thickness is exaggerated in order to illustrate that the solder pad does have a measurable thickness to it; and,

FIG. **8** is a front side elevational view thereof. The right side and rear elevational views thereof are not shown, since the symmetry of the solder pad provides right side and rear views which are the same as the left side and front views.

1 Claim, 2 Drawing Sheets

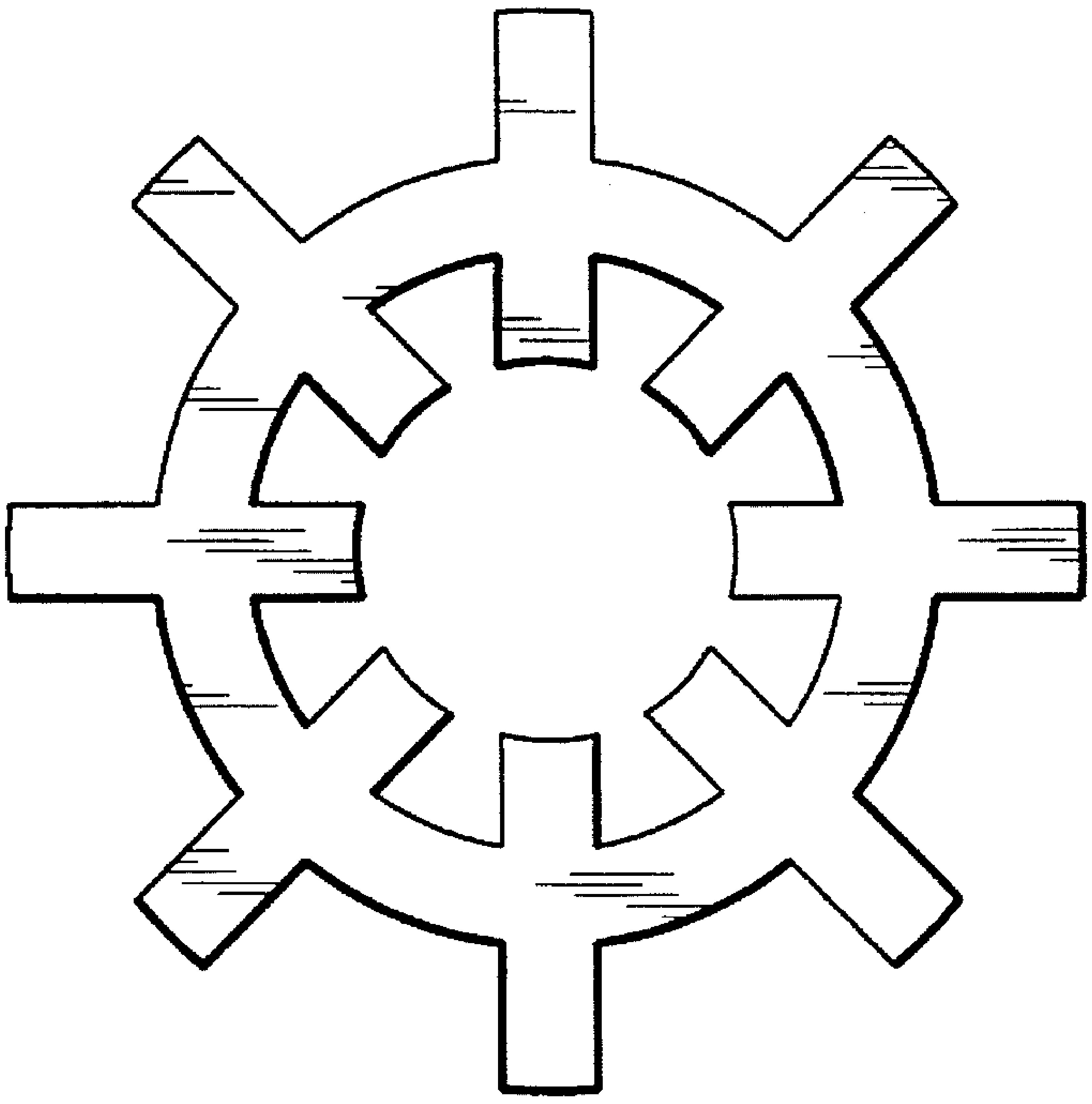

FIG. 1

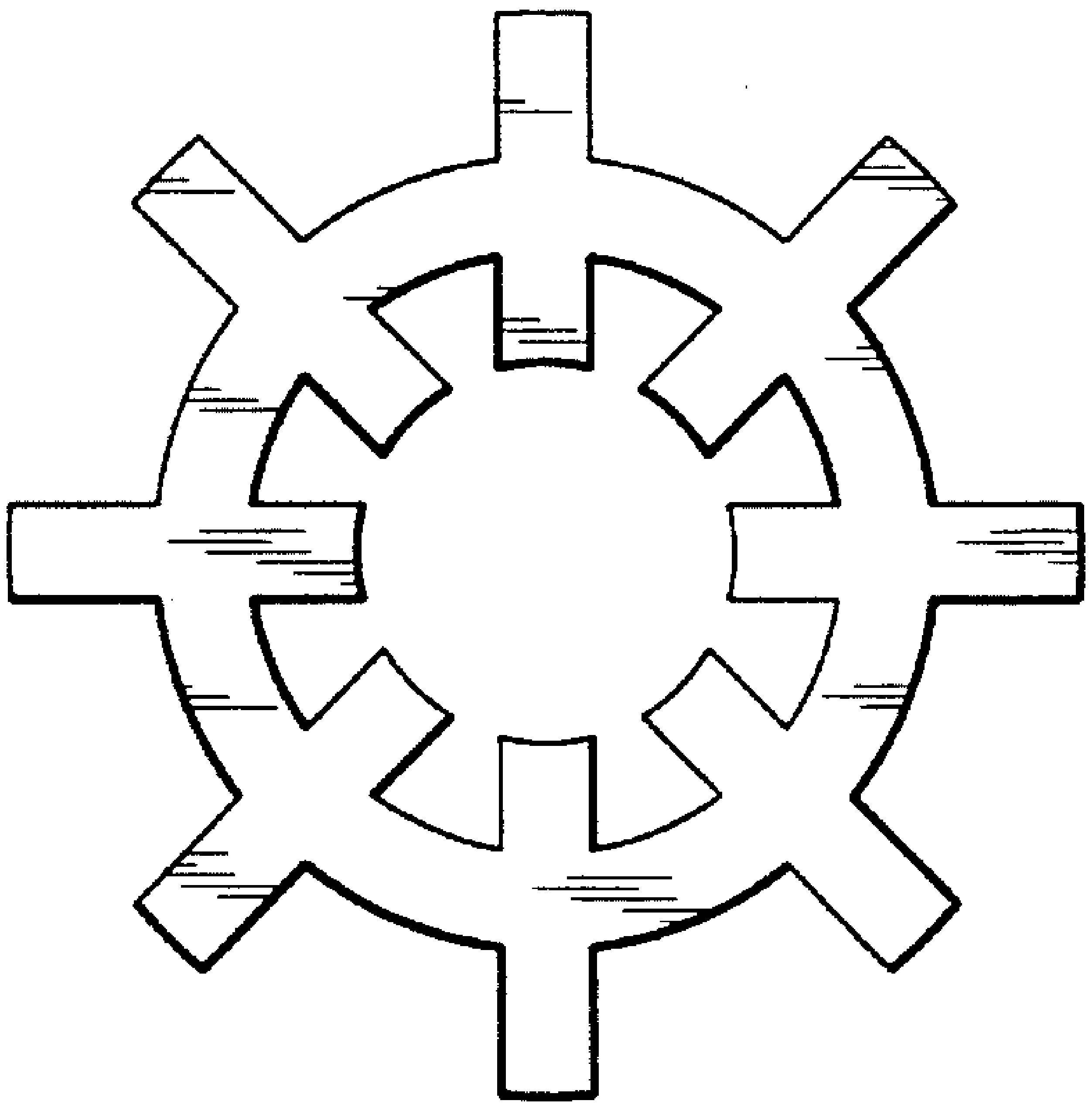

FIG. 2

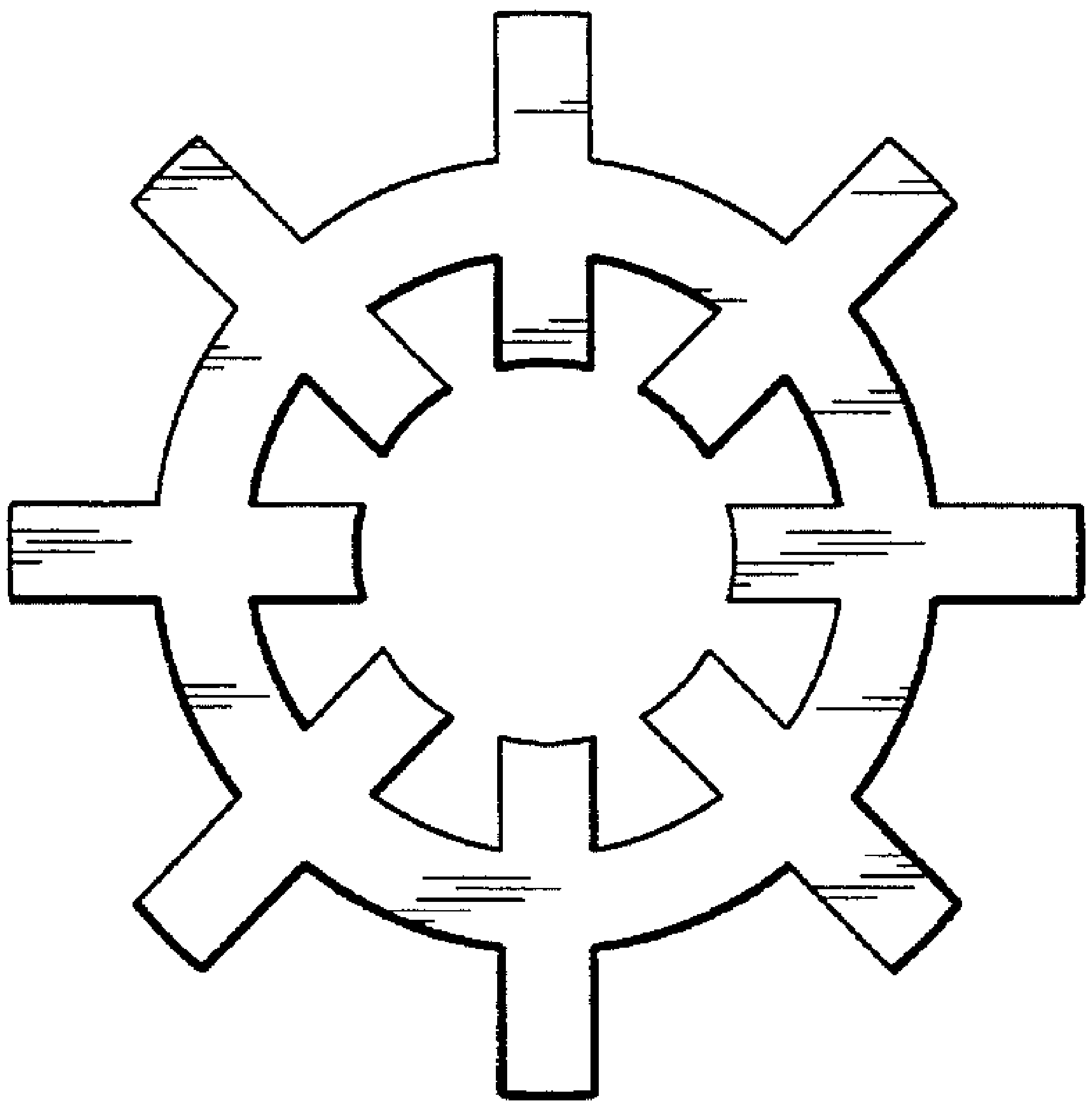

FIG. 3

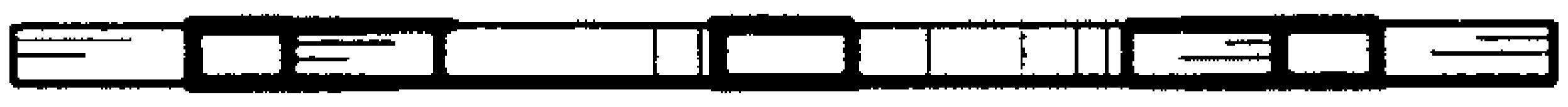

FIG. 4

FIG. 5

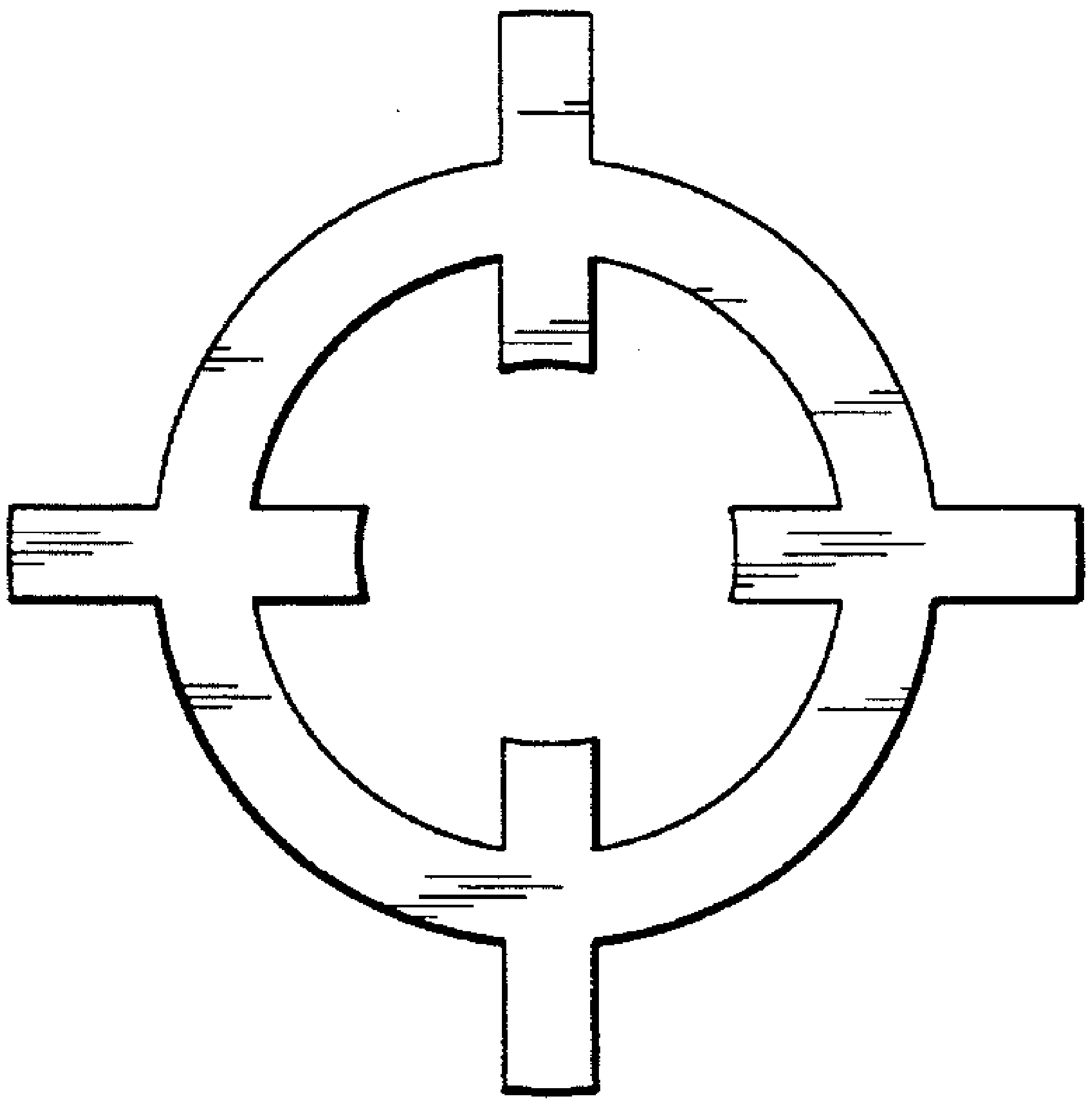

FIG. 6

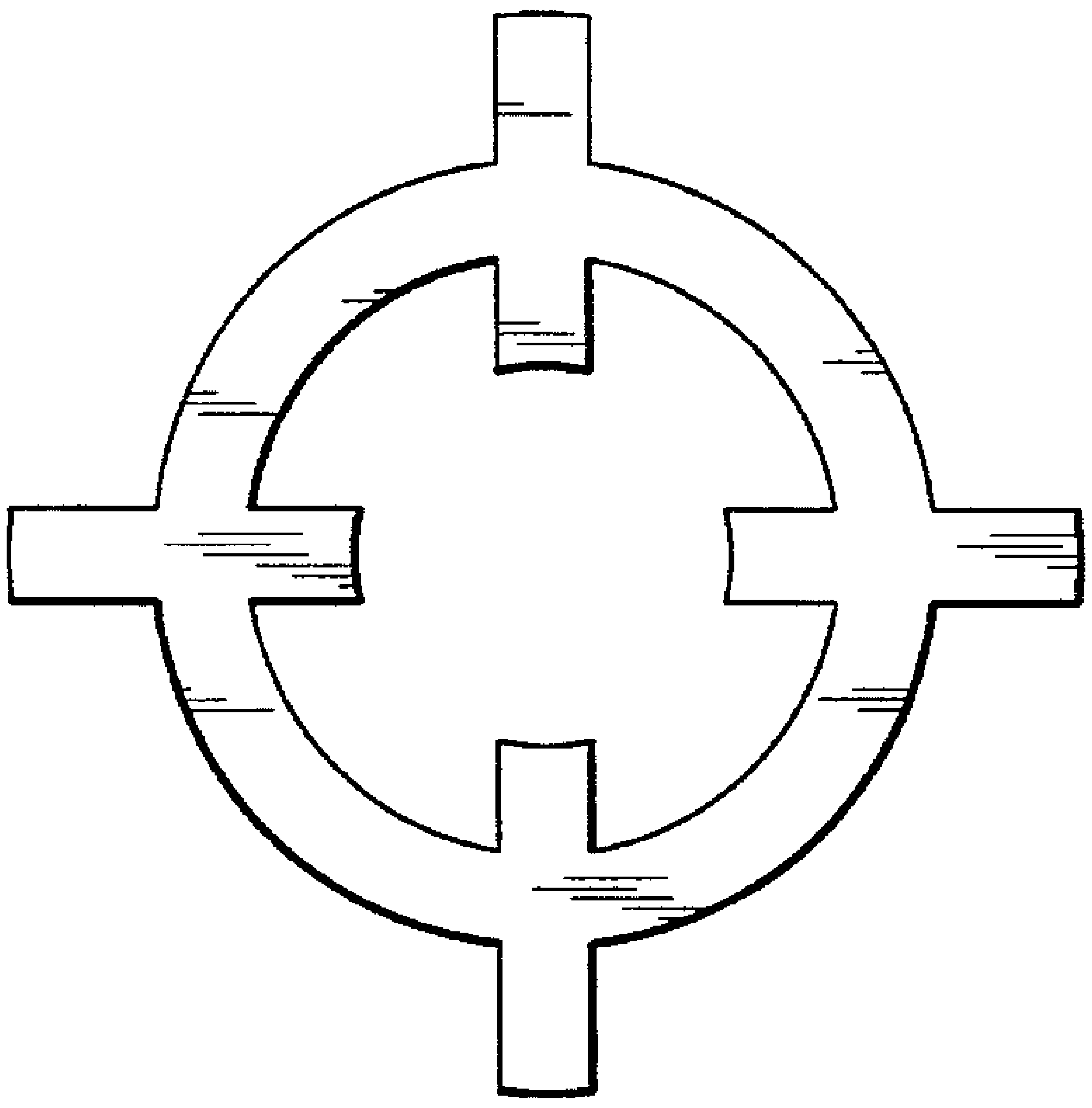

FIG. 7

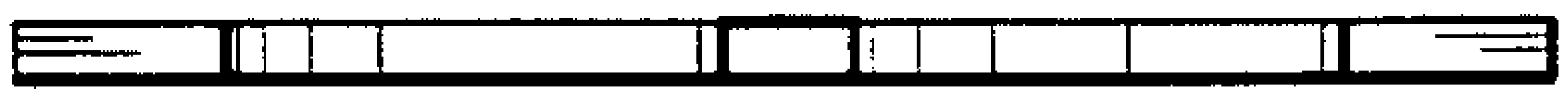

FIG. 8